有铅

Sn50/Pb50 SnPbBi

1 0.4mm
2 12
3
4
5
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6 PCB
7 ICT
8 **Paste in hole**

		ROL1	J-STD-004
		0.2wt%	
(SIR)		1 10^{13}	25mil
		1 10^{12}	40 90%RH 96Hrs
		1 10^{5}	
			IPC-TM-650
			IPC-TM-650
			In house

		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		200 Pa.s ±10% Malcolm (10rpm,2)	T3,90%metal for printing
		80 Pa.s±10% Malcolm (10rpm,2)	T4,87%metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate(Sn63,90%metal)
			J-STD-005
			In house
Vs		48gF 0	IPC-TM-650 ± 5%
		56gF 2	
		68gF 4	
		44gF 8	
		12	In house
			0~10

1

T3 mesh –325/+500 25~45 m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3 1 ;

.

3

- 有铅免洗

  0.4mm

  0.12mm

-
- 有铅免洗 80%

	60 ~ 90HS
	45^0 ~ 60^0
	2 ~ 4 10^5pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%

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PCB

PCB

A5 200g B5 300g A4 400g

4

4

5

6

此有铅

500g PE 20

35

0 ~10

-
- 0

6

MSDS